

Title (en)
Adhesive tape joining apparatus

Title (de)
KlebebandverbindungsVorrichtung

Title (fr)
Appareil de liaison de bande adhésive

Publication
EP 1962324 B1 20170510 (EN)

Application
EP 08003038 A 20080219

Priority
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Abstract (en)
[origin: EP1962324A2] An apparatus of this invention includes: a workpiece holding mechanism that holds a ring frame and a wafer; a tape supplying device that supplies a continuous dicing tape or a continuous carrier tape to which a precut dicing tape is joined, to a joining position; a joining unit that joins the continuous dicing tape or the precut dicing tape separated from the carrier tape, to the ring frame and the semiconductor wafer; a tape cutting mechanism that cuts the dicing tape joined to the ring frame along a contour of the ring frame; and a residual tape collecting section that takes up and collects a residual tape after the cutting.

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H01L 21/67 (2006.01)

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